REMARKS/ARGUMENTS

Claims 11-21 are pending in this application. By this Amendment, Applicants amend the Title of the Invention, the Abstract of the Disclosure and Claims 11-14.

The Title of the Invention was objected to for allegedly not being descriptive. Applicants have amended the Title of the Invention as suggested by the Examiner so as to be descriptive. Accordingly, Applicants respectfully request reconsideration and withdrawal of this objection.

The Abstract of the Disclosure was objected to because the Abstract allegedly is not directed to the claimed invention. Applicants have amended the Abstract of the Disclosure so as to be directed to the claimed invention. Accordingly, Applicants respectfully request reconsideration and withdrawal of this objection

Claims 11 and 13-17 were rejected under 35 U.S.C. § 102(b) as being anticipated by Yoshinaga (U.S. 5,184,043). Claims 18 and 19 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Yoshinaga in view of Kugou et al. (U.S. 5,596,244). Claims 12, 20 and 21 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Yoshinaga in view of Ikeda et al. (U.S. 6,005,329). Applicants respectfully traverse the rejections of Claim 11-21.

Claim 11 has been amended to recite:

> "A method for manufacturing an electronic component, comprising the steps of:
>
> **preparing a pair of substantially round conductive wires** defining a pair of lead terminals;
>
> bending one end portion of each of the pair of conductive wires outwards at an angle of about 90 degrees;
>
> **forming a flat portion on each of the pair of substantially round conductive wires by press extending at least the portion on a tip side from the bending point so as to be extended substantially parallel to a lead portion of a respective one of the pair of lead terminals, such that a thickness of the flat portion is less than a diameter of each of the pair of substantially round conductive wires**;
>
> forming a cup-shaped holder portion by bending the flat portion inwards;
>
> holding both end portions of a piezoelectric element in a pair of the cup-shaped holder portions; and

> electrically and mechanically connecting the cup-shaped holder portions and the electrodes formed in both end portions of the piezoelectric element by using a conductive joining material." (emphasis added)

With the unique combination of method steps and features recited in Applicants' Claim 11, including the steps of "preparing a pair of substantially round conductive wires" and "forming a flat portion on each of the pair of substantially round conductive wires by press extending at least the portion on a tip side from the bending point so as to be extended substantially parallel to a lead portion of a respective one of the pair of lead terminals, such that a thickness of the flat portion is less than a diameter of each of the pair of substantially round conductive wires," Applicants have been able to provide a method of manufacturing an electronic component in which linear lead terminals are included and in which the capability of holding piezoelectric elements and the reliability of conductivity are excellent (see, for example, the first full paragraph on page 3 of the originally filed specification).

In Section No. 6 on page 3 of the outstanding Office Action, the Examiner alleged that Yoshinaga teaches all of the method steps and features recited in Applicants' Claim 11, including the step of "forming a flat portion by press extending at least the portion on the tip side from the bending point so as to be extended substantially parallel to a lead portion of the lead terminal (20, 30)."

Applicants' Claim 11 has been amended to recite the method steps of "preparing a pair of substantially round conductive wires" and "forming a flat portion on each of the pair of substantially round conductive wires by press extending at least the portion on a tip side from the bending point so as to be extended substantially parallel to a lead portion of a respective one of the pair of lead terminals, such that a thickness of the flat portion is less than a diameter of each of the pair of substantially round conductive wires." Support for these steps is found, for example, in the Fig. 3 and the first full paragraph on page 5 of the originally filed specification.

As clearly seen in Fig 4 of Yoshinaga, the terminals 20, 30 of Yoshinaga, which the Examiner alleged correspond to the conductive wires recited in Applicants' Claim 11, are punched from a flat metallic plate, and accordingly, each of the terminals 20, 30 of Yoshinaga has a **flat** cross-section, **NOT** a **substantially round** cross-section. In addition, as seen in Fig. 4 of Yoshinaga, each of the terminals 20, 30 has a consistent thickness over the entire length of the terminal, and neither of the terminals 20, 30 of Yoshinaga includes any portion having a reduced thickness. Furthermore, Yoshinaga neither teaches nor suggests that the terminals 20, 30 could or should have any other shape other than a flat plate shape.

Thus, Yoshinaga certainly fails to teach or suggest the method steps of "preparing a pair of **substantially round** conductive wires" and "**forming a flat portion on each of the pair of substantially round conductive wires** by press extending at least the portion on a tip side from the bending point so as to be extended substantially parallel to a lead portion of a respective one of the pair of lead terminals, **such that a thickness of the flat portion is less than a diameter of each of the pair of substantially round conductive wires**" (emphasis added) as recited in Applicants' Claim 11.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of Claim 11 under 35 U.S.C. § 102(b) as being anticipated by Yoshinaga.

The Examiner relied upon Kugou et al. and Ikeda et al. to allegedly cure various deficiencies of Yoshinaga. However, neither Kugou et al. nor Ikeda et al. teaches or suggests the steps of "preparing a pair of substantially round conductive wires" and "forming a flat portion on each of the pair of substantially round conductive wires by press extending at least the portion on a tip side from the bending point so as to be extended substantially parallel to a lead portion of a respective one of the pair of lead terminals, such that a thickness of the flat portion is less than a diameter of each of the pair of substantially round conductive wires" as recited in Applicants' Claim 11. Thus, Applicants respectfully submit that Kugou et al. and Ikeda et al. fail to cure the deficiencies of Yoshinaga described above.

Accordingly, Applicants respectfully submit that Yoshinaga, Kugou et al. and Ikeda et al., applied alone or in combination, fail to teach or suggest the unique combination of method steps and features recited in Applicants' Claim 11.

In view of the foregoing amendments and remarks, Applicants respectfully submit that Claim 11 is allowable. Claims 12-21 depend upon Claim 11, and are therefore allowable for at least the reasons that Claim 11 is allowable.

In view of the foregoing amendments and remarks, Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt allowance are solicited.

To the extent necessary, Applicants petition the Commissioner for a One-Month Extension of Time, extending to April 6, 2006, the period for response to the Office Action dated December 6, 2005.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

Dated: April 6, 2006

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